



Assembly Location and Mold Compound Change for Platform Flash TSOP48 Packages

XCN07015 (v1.0.1) September 7, 2007

Product Change Notice

Overview

This notice describes two changes to the 8-Mbit, 16-Mbit, and 32-Mbit Platform Flash devices of the Xilinx In-System Programmable Configuration PROMs manufactured by ST Microelectronics:

- Assembly and finish plant location change for all TSOP48 packages (VO48 and VOG48) from the current ST Microelectronics Toa Payoh, Singapore location to the ST Microelectronics Muar, Malaysia location.
- Consolidation of mold compound material to ensure use of the same mold compound across all TSOP48 packages. The mold compound for VOG48 (Pb-free) packages will be changed to be the same as the mold compound already in volume production for the Xilinx standard, VO48 (not Pb-free) products.

There is no change to the form, fit, or function of these devices.

Description

The TSOP48 assembly and finish plant is being moved from the ST Microelectronics Toa Payoh, Singapore location to the ST Microelectronics Muar, Malaysia location. As a part of this transition, the molding compound used for the Platform Flash VOG48 Pb-free packages is also being changed from Sumitomo SumiG700 to Kyocera KE-3300D. The Kyocera KE-3300D mold compound material is used in the standard (non Pb-free) VO48 Platform Flash products which have been shipping in volume production since 2005.

These consolidations are designed to make Platform Flash manufacturing more efficient and timely, enabling smoother supply to Xilinx customers. This is not a process or technology change and has no impact to form, fit, or function of the products.

Products Affected

This notification applies only to the following Xilinx commercial part numbers (see [Table 1](#)). Please reference the [Traceability](#) section for further information on identifying these products.

Table 1: Affected Devices

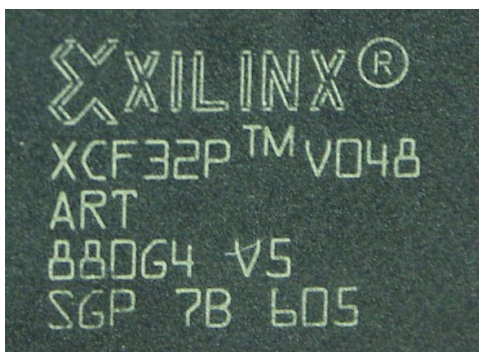
Assembly Plant Migration		
Device	Device	Device
XCF08PVO48C	XCF16PVO48C	XCF32PVO48C
XCF08PVOG48C	XCF16PVOG48C	XCF32PVOG48C
Mold Compound change to Kyocera KE-3300D		
Device	Device	Device
XCF08PVOG48C	XCF16PVOG48C	XCF32PVOG48C

Key Dates and Ordering Information

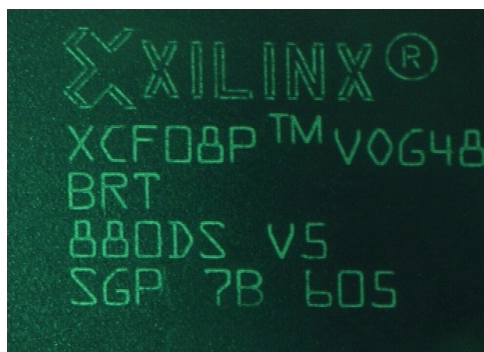
Product with the updated VOG48 material set, and the new assembly and finish location in Muar, Malaysia is estimated to begin shipping on, or after, November 12, 2007 (date code 0746). Product from the Toa Payoh, Singapore location will stop shipping upon inventory depletion.

Traceability

A top mark facilitates package traceability. The date code change can be found on the package top mark as shown in [Figure 1](#) and [Table 2](#).



XCF32P



XCF08P & XCF16P

XCN07015_01_072407

Figure 1: Top Mark Detail

Table 2: Top Mark Detail

Current Marking	New Marking
'88' : Assembly plant code	'99' : New assembly plant code
'SGP' : Country of Origin - Singapore	'MYS' : New Country of Origin - Malaysia
'605' : workweek05, 2006	'YWW' : workweekWW, 200Y

Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

Important Notice: Xilinx Customer Notices (XCNs, XDNs, and Quality Alerts) can be delivered via e-mail alerts sent by the MySupport website (<http://www.xilinx.com/support>). Register today and personalize your “MyAlerts” area to include Customer Notices. This change provides many benefits, including the ability to receive alerts for new and updated information about specific products, as well as alerts for other publications such as data sheets, errata, application notes, etc. For information on how to sign up, refer to [Xilinx Answer Record 18683](#).

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
08/06/07	1.0	Initial Xilinx release.
09/07/07	1.0.1	Corrected typo; KY-3300D changed to KE-3300D.